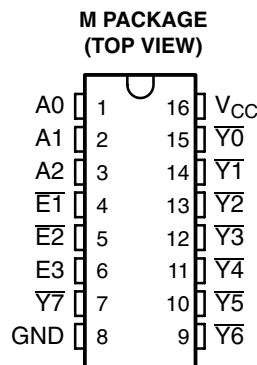


CD74HC138-Q1
HIGH-SPEED CMOS LOGIC
3- TO 8-LINE INVERTING DECODER/DEMULTIPLEXER
 SCLS580A – APRIL 2004 – REVISED APRIL 2008

- Qualified for Automotive Applications
- Select One of Eight Data Outputs Active Low
- I/O Port or Memory Selector
- Three Enable Inputs to Simplify Cascading
- Typical Propagation Delay of 13 ns at $V_{CC} = 5\text{ V}$, $C_L = 15\text{ pF}$, $T_A = 25^\circ\text{C}$
- Fanout (Over Temperature Range)
 - Standard Outputs . . . 10 LSTTL Loads
 - Bus Driver Outputs . . . 15 LSTTL Loads
- Balanced Propagation Delay and Transition Times
- Significant Power Reduction Compared to LSTTL Logic ICs
- 2-V to 6-V V_{CC} Operation
- High Noise Immunity; N_{IL} or $N_{IH} = 30\%$ of V_{CC} , $V_{CC} = 5\text{ V}$



description/ordering information

The CD74HC138 is a high-speed silicon-gate CMOS decoder well suited to memory address decoding or data routing applications. This circuit features low power consumption usually associated with CMOS circuitry, yet has speeds comparable to low-power Schottky TTL logic. The circuit has three binary select inputs (A0, A1, and A2). If the device is enabled, these inputs determine which one of the eight normally high outputs of the HC138 will go low.

Two active-low and one active-high enables ($\overline{E1}$, $\overline{E2}$, and E3) are provided to ease the cascading of decoders. The decoder's eight outputs can drive ten low-power Schottky TTL equivalent loads.

ORDERING INFORMATION[†]

T_A	PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	SOIC – M	Reel of 2500	CD74HC138QM96Q1	HC138Q

[†] For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at <http://www.ti.com>.

[‡] Package drawings, thermal data, and symbolization are available at <http://www.ti.com/packaging>.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2008, Texas Instruments Incorporated

CD74HC138-Q1

HIGH-SPEED CMOS LOGIC

3- TO 8-LINE INVERTING DECODER/DEMULTIPLEXER

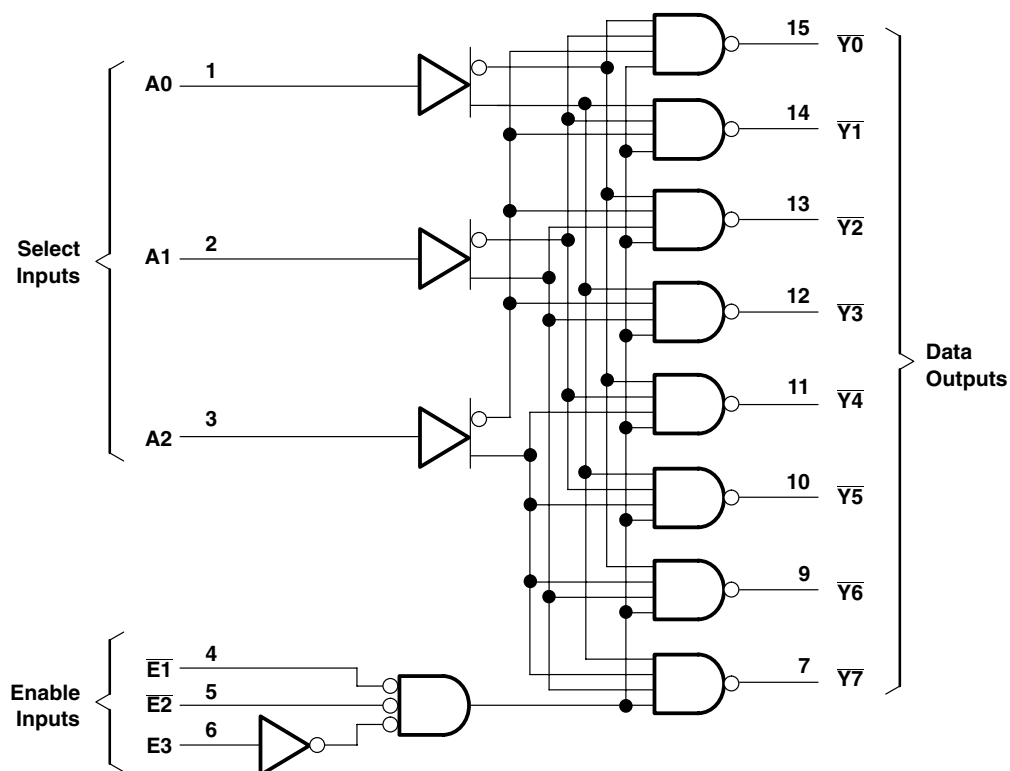
SCLS580A – APRIL 2004 – REVISED APRIL 2008

FUNCTION TABLE

ENABLE INPUTS			SELECT INPUTS			OUTPUTS							
E3	E2	E1	A2	A1	A0	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
X	X	H	X	X	X	H	H	H	H	H	H	H	H
L	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X	X	X	X	H	H	H	H	H	H	H	H
H	L	L	L	L	L	L	H	H	H	H	H	H	H
H	L	L	L	L	H	H	L	H	H	H	H	H	H
H	L	L	L	H	L	H	H	L	H	H	H	H	H
H	L	L	L	H	H	H	H	L	H	H	H	H	H
H	L	L	H	L	L	H	H	H	H	L	H	H	H
H	L	L	H	L	H	H	H	H	H	H	L	H	H
H	L	L	H	H	L	H	H	H	H	H	H	L	H
H	L	L	H	H	H	H	H	H	H	H	H	H	L

NOTE: H = High voltage level, L = Low voltage level, X = Don't care

logic diagram (positive logic)



CD74HC138-Q1
HIGH-SPEED CMOS LOGIC
3- TO 8-LINE INVERTING DECODER/DEMULTIPLEXER
SCLS580A – APRIL 2004 – REVISED APRIL 2008

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.5 V to 7 V
Input clamp current, I_{IK} ($V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V)	± 20 mA
Output clamp current, I_{OK} ($V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V)	± 20 mA
Source or sink current per output pin, I_O ($V_O > -0.5$ V or $V_O < V_{CC} + 0.5$ V)	± 25 mA
Continuous current through V_{CC} or GND	± 50 mA
Package thermal impedance, θ_{JA} (see Note 2)	73°C/W
Storage temperature range, T_{stg}	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltages referenced to GND unless otherwise specified.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
V_{CC}	Supply voltage		2	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		V
		$V_{CC} = 4.5$ V	3.15		
		$V_{CC} = 6$ V	4.2		
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V		0.5	V
		$V_{CC} = 4.5$ V		1.35	
		$V_{CC} = 6$ V		1.8	
V_I	Input voltage		0	V_{CC}	V
V_O	Output voltage		0	V_{CC}	V
t_t	Input transition (rise and fall) time	$V_{CC} = 2$ V	0	1000	ns
		$V_{CC} = 4.5$ V	0	500	
		$V_{CC} = 6$ V	0	400	
T_A	Operating free-air temperature		–40	125	°C

- NOTES: 3. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

CD74HC138-Q1
HIGH-SPEED CMOS LOGIC
3- TO 8-LINE INVERTING DECODER/DEMULTIPLEXER

SCLS580A – APRIL 2004 – REVISED APRIL 2008

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		I _O (mA)	V _{CC}	T _A = 25°C			T _A = -40°C TO 125°C		UNIT
					MIN	TYP	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	CMOS loads	-0.02	2 V	1.9			1.9	V	
			-0.02	4.5 V	4.4			4.4		
			-0.02	6 V	5.9			5.9		
		TTL loads	-4	4.5 V	3.98			3.7		
			-5.2	6 V	5.48			5.2		
V _{OL}	V _I = V _{IH} or V _{IL}	CMOS loads	0.02	2 V			0.1	0.1	V	
			0.02	4.5 V			0.1	0.1		
			0.02	6 V			0.1	0.1		
		TTL loads	4	4.5 V			0.26	0.4		
			5.2	6 V			0.26	0.4		
I _I	V _I = V _{CC} or GND			6 V			±0.1	±1	μA	
I _{CC}	V _I = V _{CC} or GND		0	6 V			8	160	μA	
C _{IN}							10	10	pF	

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	V_{CC}	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C}$ TO 125°C		UNIT
					MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 15\text{ pF}$	5 V		13				ns
				2 V			150		225	
			$C_L = 50\text{ pF}$	4.5 V			30		45	
				6 V			26		38	
	E	Y	$C_L = 50\text{ pF}$	2 V			150		265	
				4.5 V			30		53	
				6 V			26		45	
t_t		Y	$C_L = 50\text{ pF}$	2 V			75		110	ns
				4.5 V			15		22	
				6 V			13		19	

operating characteristics, $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, Input t_r , $t_f = 6\text{ ns}$, $C_L = 15\text{ pF}$

PARAMETER		TYP	UNIT
C_{pd}	Power dissipation capacitance (see Note 4)	67	pF

NOTE 4: C_{pd} is used to determine the dynamic power consumption, per gate.

$$P_D = V_{CC}^2 f_i (C_{pd} + C_L)$$

f_i = input frequency

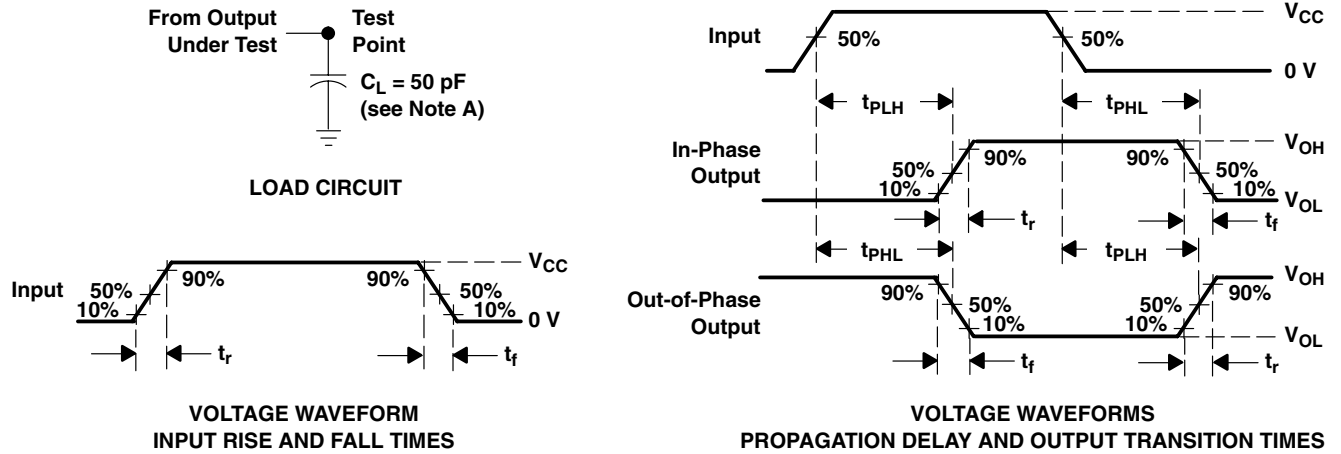
C_L = output load capacitance

V_{CC} = supply voltage



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and test-fixture capacitance.
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r = 6 \text{ ns}$, $t_f = 6 \text{ ns}$.
 C. The outputs are measured one at a time, with one input transition per measurement.
 D. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CD74HC138QM96Q1	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC138Q
CD74HC138QM96Q1.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC138Q

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD74HC138-Q1 :

- Catalog : [CD74HC138](#)

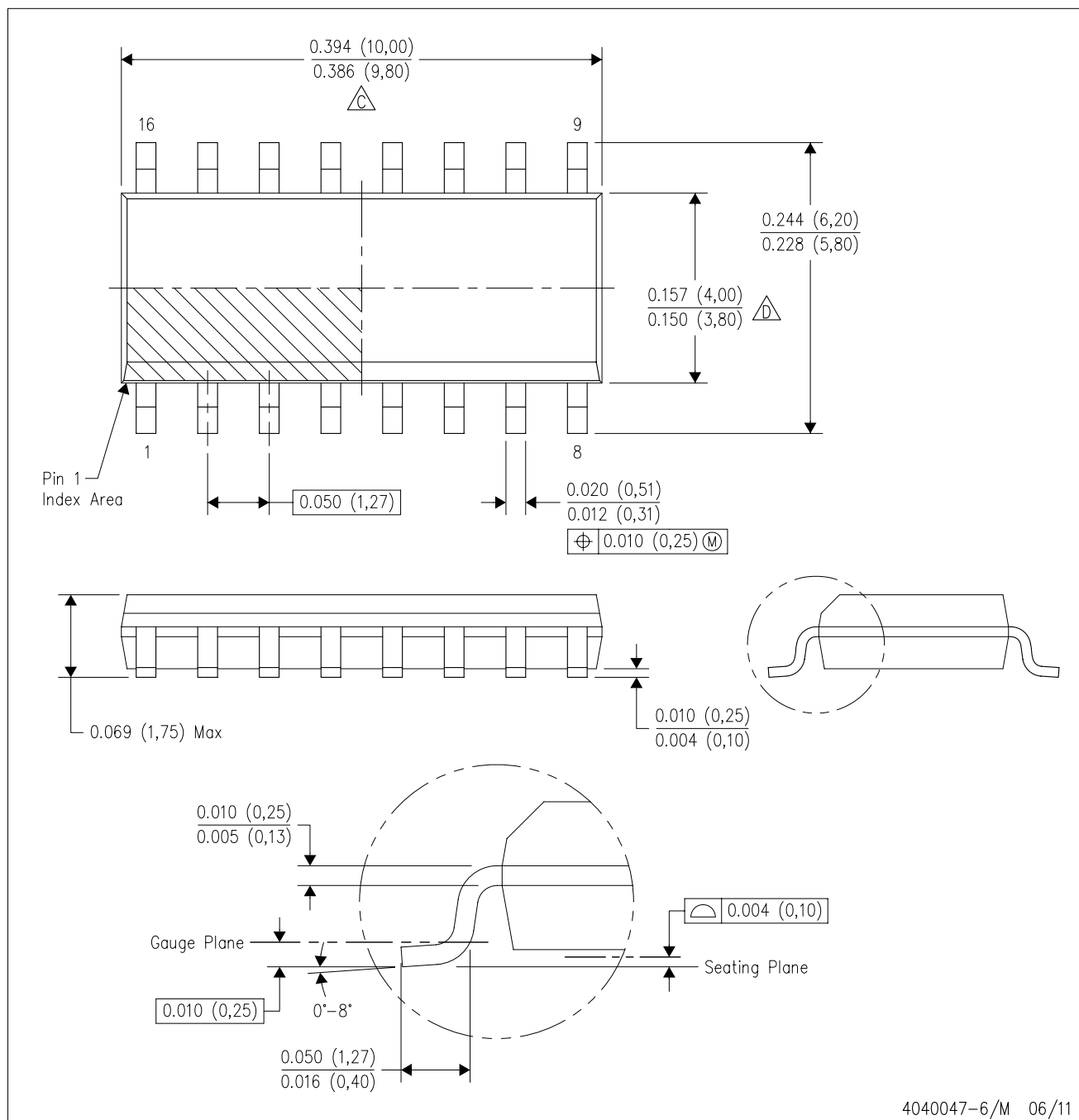
- Military : [CD54HC138](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



4040047-6/M 06/11

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025